

TSF

Tacky Solder Fluxes

TSF-6522RH

TSF-6522RH IS A ROSIN BASED, NO-CLEAN TACKY SOLDERING FLUX FORMULA DESIGNED TO BE COMPLIANT WITH IEC 61249-2-21 DEFINITION FOT HALIDE-FREE MATERIALS AND FEATURES

- Highly active and good solderability performance
- High tack values and long tack life
- 6 month shelf life
- Halogen-Free formulation
- Can reflow in air and nitrogen environments
- Designed for printing and dipping application



TSF-URL18

TSF-URL18 IS A NO-CLEAN, ULTRA RESIDUE TACKY FLUX FEATURING

- Support Flip Chip on Lead Frame, Ultra Fine Pitch Cu Pillar Bump and Micro-Solder Bumps, 2.5D, 3D Packaging
- Room temperature storage condition (0-30 ° C)
- Post reflow residue of below 10% wt
- Halogen-Free and Zero-Halogen formulations
- Long pot life (24 hours)
- 12 month shelf life
- Underfill and mold compound compatible
- Good wetting, solderability and solder bridging performance

TSF-WS917

TSF-WS917 IS A WATER-SOLUBLE TACKY SOLDERING FLUX FORMULA WITH A UNIQUE HALOGEN-FREE ACTIVATOR SYSTEM FEATURING

- 12 month shelf life
- 24 hour pot life
- Room temperature storage condition (0-30 ° C)
- Halogen-Free
- Reflowable in air and nitrogen
- Post reflow residues are easily removed with hot DI (40° C)
- Highly active and strong solderability performance



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